

DSA8003

Silicon PNP epitaxial planar type

For low frequency output amplification
DSA7003 in MT-2 through hole type package

■ Features

- Low collector-emitter saturation voltage $V_{CE(sat)}$
- Contributes to miniaturization of sets, mount area reduction
- Eco-friendly Halogen-free package

■ Packaging

Radial type : 2000 pcs / carton

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|---------------------------------------|-----------|-------------|------------------|
| Collector-base voltage (Emitter open) | V_{CBO} | -60 | V |
| Collector-emitter voltage (Base open) | V_{CEO} | -50 | V |
| Emitter-base voltage (Collector open) | V_{EBO} | -5 | V |
| Collector current | I_C | -1 | A |
| Peak collector current | I_{CP} | -1.5 | A |
| Collector power dissipation * | P_C | 1 | W |
| Junction temperature | T_j | 150 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -55 to +150 | $^\circ\text{C}$ |

Note) *: Printed circuit board: Copper foil area of 1 cm² or more, and the board thickness of 1.7 mm for the collector portion

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|---|---------------|--|-----|------|------|---------------|
| Collector-base voltage (Emitter open) | V_{CBO} | $I_C = -10 \mu\text{A}, I_E = 0$ | -60 | | | V |
| Collector-emitter voltage (Base open) | V_{CEO} | $I_C = -2 \text{ mA}, I_B = 0$ | -50 | | | V |
| Emitter-base voltage (Collector open) | V_{EBO} | $I_E = -10 \mu\text{A}, I_C = 0$ | -5 | | | V |
| Collector-base cutoff current (Emitter open) | I_{CBO} | $V_{CB} = -20 \text{ V}, I_E = 0$ | | | -0.1 | μA |
| Forward current transfer ratio *1 | h_{FE1} *2 | $V_{CE} = -10 \text{ V}, I_C = -500 \text{ mA}$ | 120 | | 340 | — |
| | h_{FE2} | $V_{CE} = -5 \text{ V}, I_C = -1 \text{ A}$ | 50 | | | — |
| Collector-emitter saturation voltage *1 | $V_{CE(sat)}$ | $I_C = -500 \text{ mA}, I_B = -50 \text{ mA}$ | | | -0.4 | V |
| Base-emitter saturation voltage *1 | $V_{BE(sat)}$ | $I_C = -500 \text{ mA}, I_B = -50 \text{ mA}$ | | | -1.2 | V |
| Transition frequency | f_T | $V_{CE} = -10 \text{ V}, I_C = -50 \text{ mA}$ | | 120 | | MHz |
| Collector output capacitance (Common base, input open circuited) | C_{ob} | $V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$ | | 14.5 | 30 | pF |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *1: Pulse measurement

*2: Rank classification

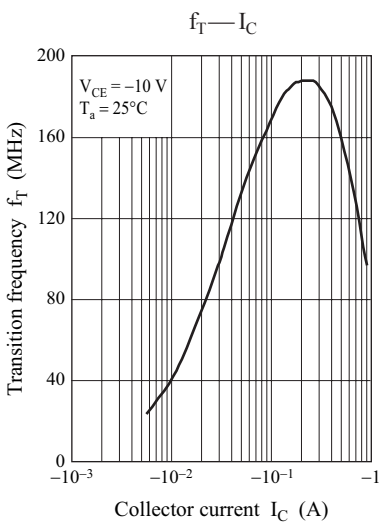
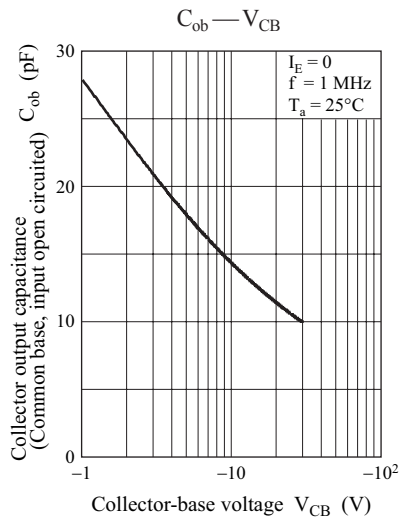
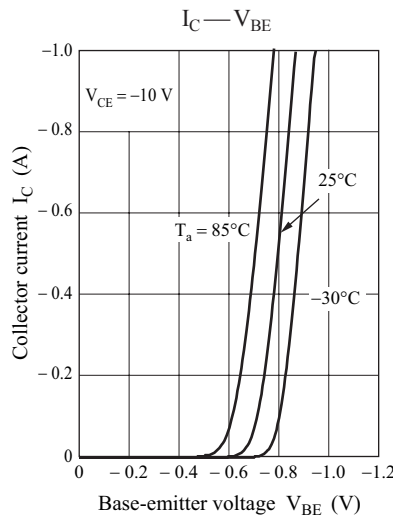
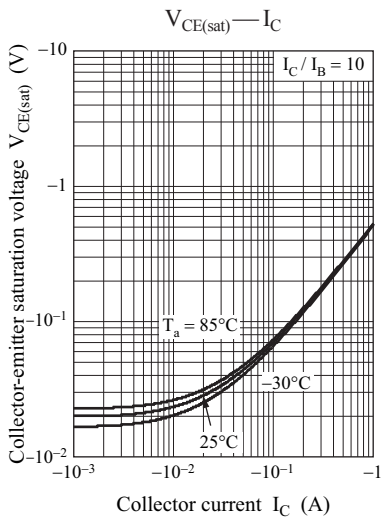
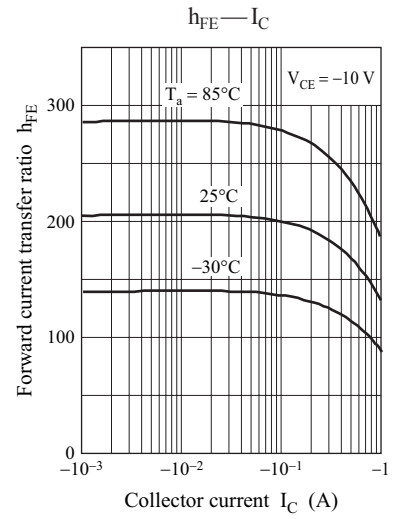
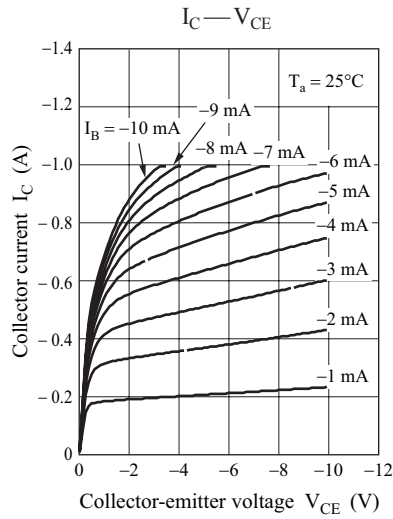
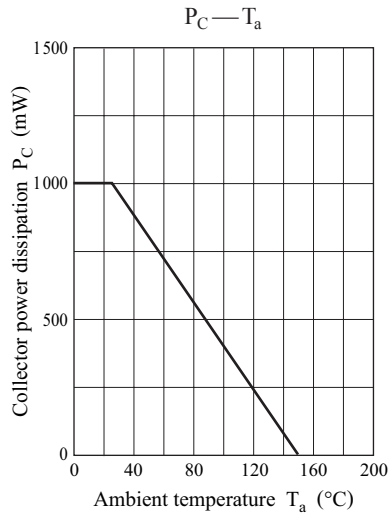
| Code | R | S | 0 |
|----------------|------------|------------|------------|
| Rank | R | S | No-rank |
| h_{FE1} | 120 to 240 | 170 to 340 | 120 to 340 |
| Marking Symbol | 4AR | 4AS | 4A |

Product of no-rank is not classified and have no marking symbol for rank.

■ Package

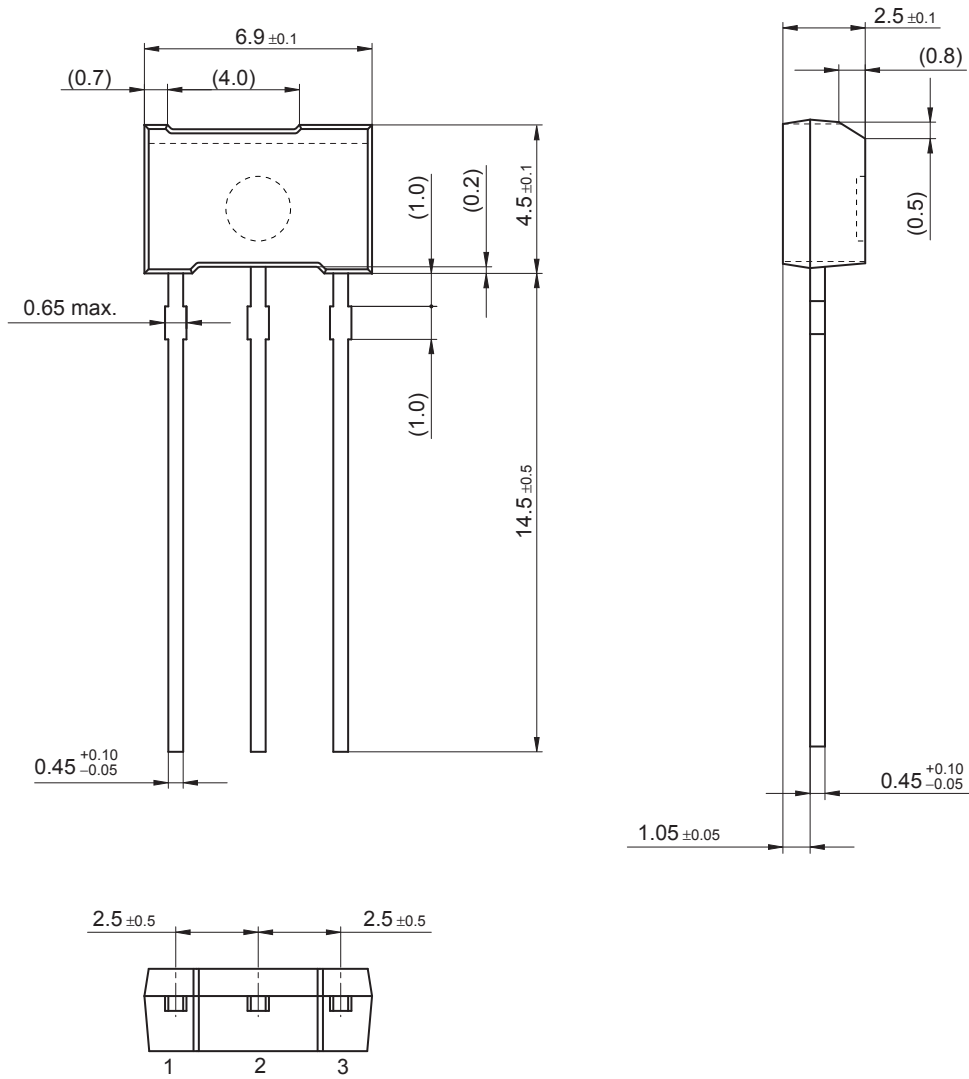
- Code
MT-2-A2-B
- Pin Name
 1. Emitter
 2. Collector
 3. Base

■ Marking Symbol: 4A



MT-2-A2-B

Unit: mm



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